

Product Summary

V _{(BR)DSS}	R _{D(on)MAX}	I _D
30V	5.8mΩ@10V	60A
	8mΩ@4.5V	

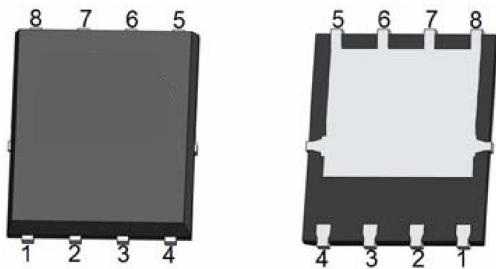
Feature

- Fast Switching
- Low Gate Charge and Rdson
- Low Reverse transfer capacitances
- 100% Single Pulse avalanche energy Test

Application

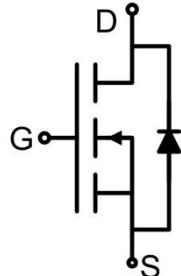
- Power switching application
- Isolated DC/DC Converters in Telecom and Industrial

Package

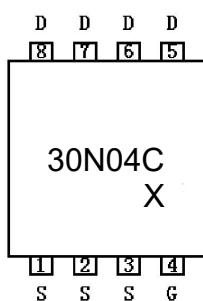


DFN5X6-8L

Circuit diagram



Marking



Absolute maximum ratings (Ta=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current (T _c =25°C) ¹⁾	I _D	60	A
Continuous Drain Current (T _c =100°C) ¹⁾	I _D	38	A
Pulsed Drain Current ²⁾	I _{IDM}	240	A
Power Dissipation ⁴⁾	P _D	87	W
Thermal Resistance ,Junction-to-Ambient ¹⁾	R _{θJA}	50	°C/W
Thermal Resistance,Junction-to-Case ¹⁾	R _{θJC}	1.5	°C/W
Single pulse avalanche energy ³⁾	E _{AS}	20	mJ
Junction Temperature	T _J	-55 ~ +150	°C
Storage Temperature	T _{STG}	-55 ~ +150	°C

Electrical characteristics (Ta=25 °C, unless otherwise noted)

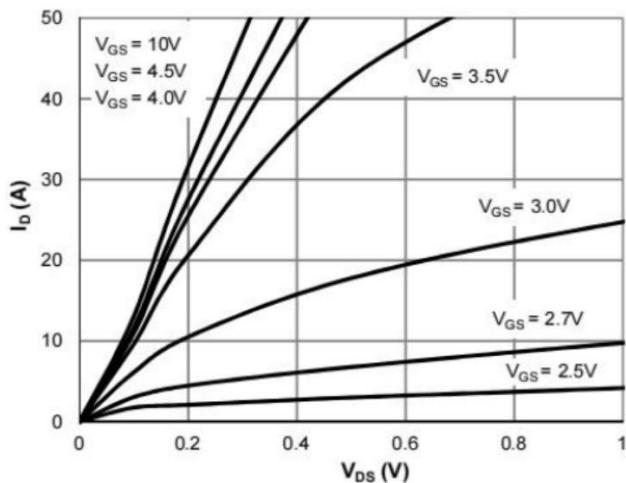
Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D =250uA	30	-	-	V
Drain-source Leakage current	I _{DSS}	V _{DS} =24V,V _{GS} = 0V TJ=25°C	-	-	1	µA
Gate-body leakage current	I _{GSS}	V _{GS} =±20V, V _{DS} = 0V	-	-	±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250µA	1.0	1.7	2.5	V
Drain-source on-resistance ²⁾	R _{DS(on)}	V _{GS} =10V, I _D =15A	-	4	5.8	mΩ
		V _{GS} =4.5V, I _D =10A	-	6	8	
Dynamic characteristics						
Input Capacitance	C _{iss}	V _{DS} =15V,V _{GS} =0V,f =1MHz	-	1109	-	pF
Output Capacitance	C _{oss}		-	240	-	
Reverse Transfer Capacitance	C _{rss}		-	220	-	
Total Gate Charge(4.5V)	Q _g	V _{DS} =15V,V _{GS} =10V, I _D =15A	-	6.7	-	nC
Gate-Source Charge	Q _{gs}		-	2.1	-	
Gate-Drain Charge	Q _{gd}		-	2.0	-	
Turn-on delay time	t _{d(on)}	V _{DD} =15V,V _{GS} =10V, I _D =15A,R _{GEN} =6Ω	-	2.4	-	nS
Turn-on rise time	t _r		-	2.5	-	
Turn-off delay time	t _{d(off)}		-	12.7	-	
Turn-off fall time	t _f		-	6.9	-	
Source-Drain Diode characteristics						
Diode Forward Current ^{1),5)}	I _S		-	-	60	A
Diode Forward voltage ²⁾	V _{SD}	V _{GS} =0V, I _S =1A, TJ =25°C	-	-	1.2	V

Notes:

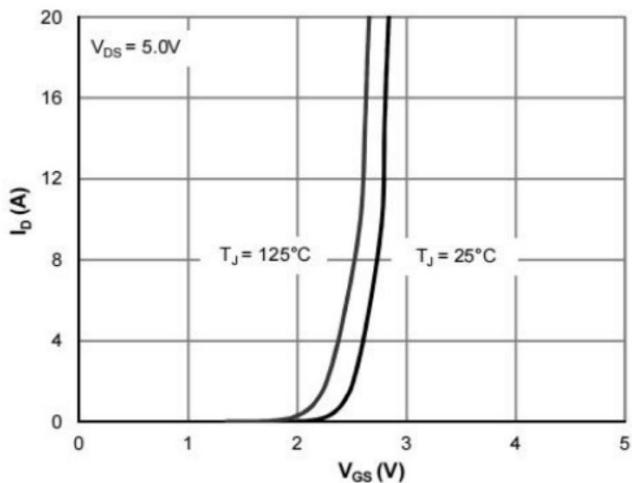
- 1) The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2) The data tested by pulsed , pulse width ≤ 300us , duty cycle≤2%.
- 3) The EAS data shows Max. rating . The test condition is VDD=25V,VGS=10V,L=0.1mH,IAS=20A.
- 4) The power dissipation is limited by 150°C junction temperature.
- 5) The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.



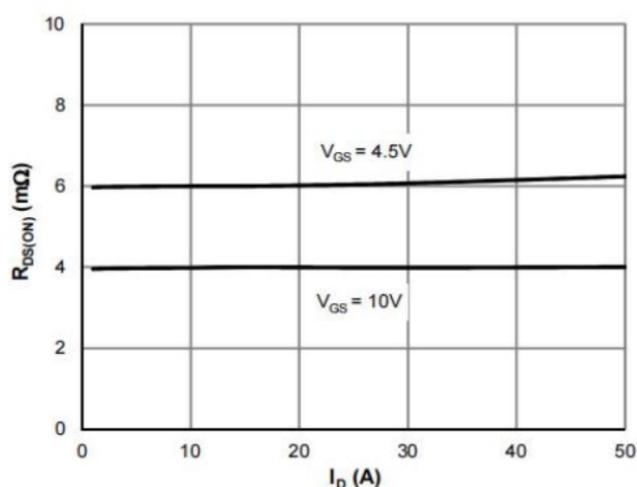
Typical Characteristics



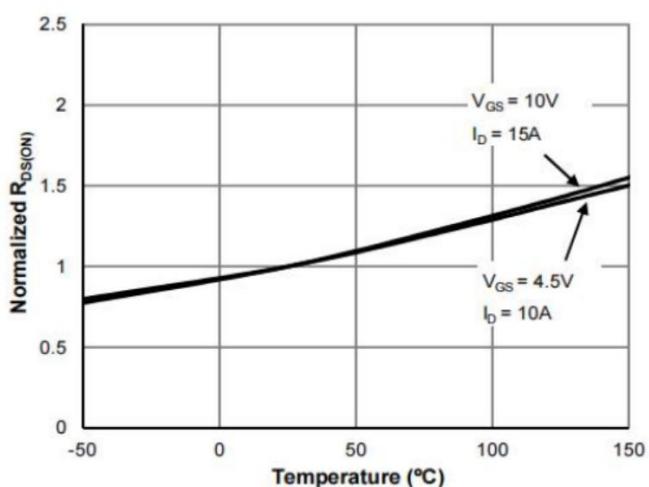
Typical Output Characteristics



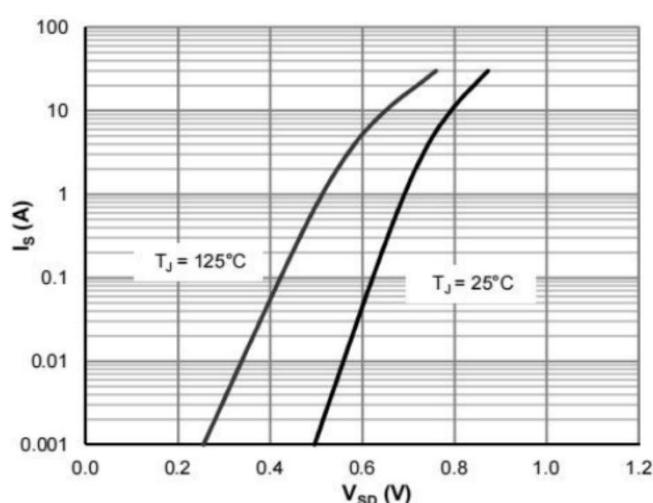
Transfer Characteristics



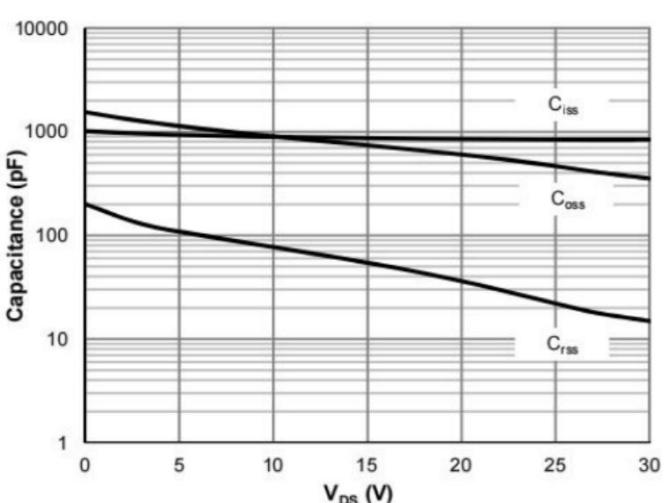
RDS(ON) vs. Drain Current



RDS(ON) vs. Junction Temperature

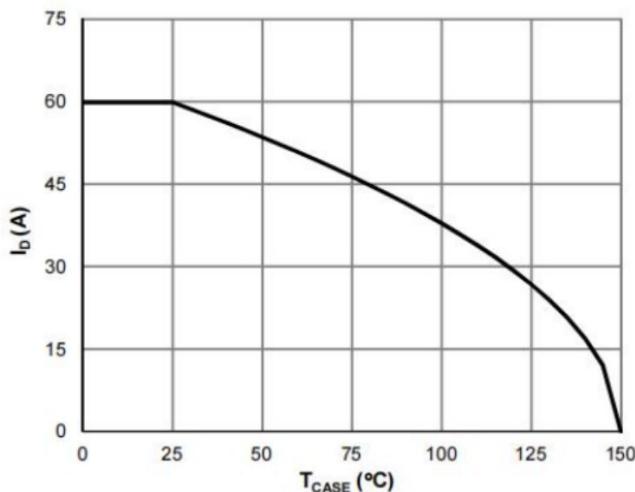


Body-Diode Characteristics

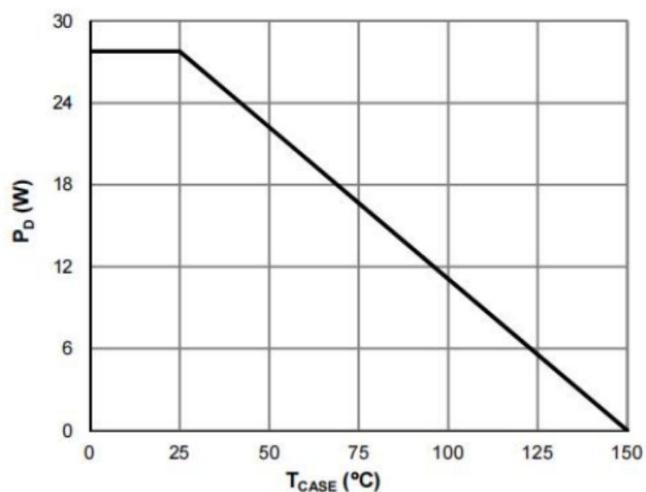


Capacitance Characteristics

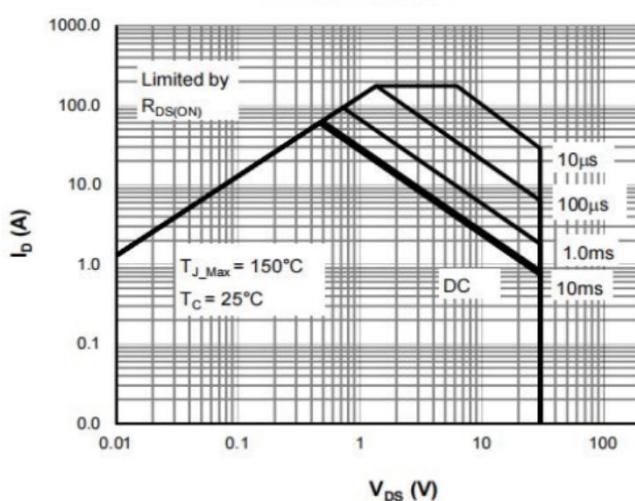
Typical Characteristics



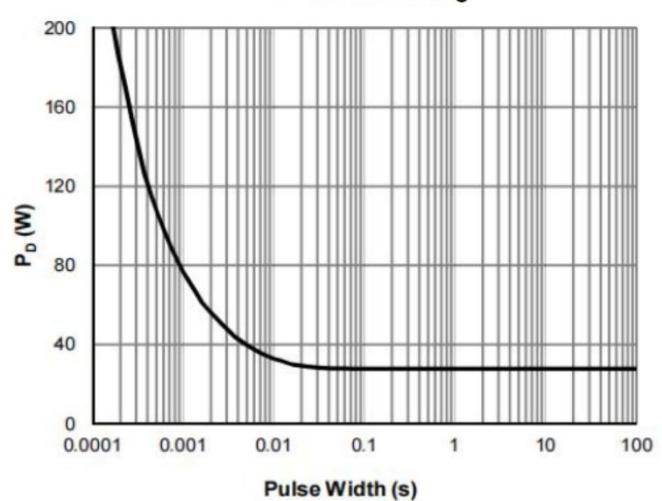
Current De-rating



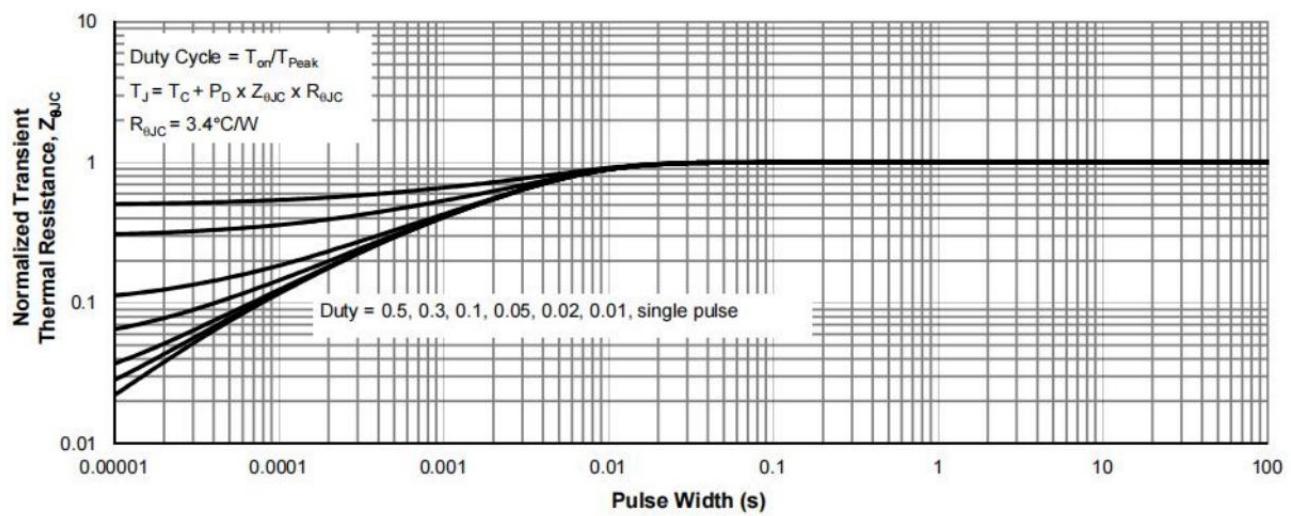
Power De-rating



Maximum Safe Operating Area

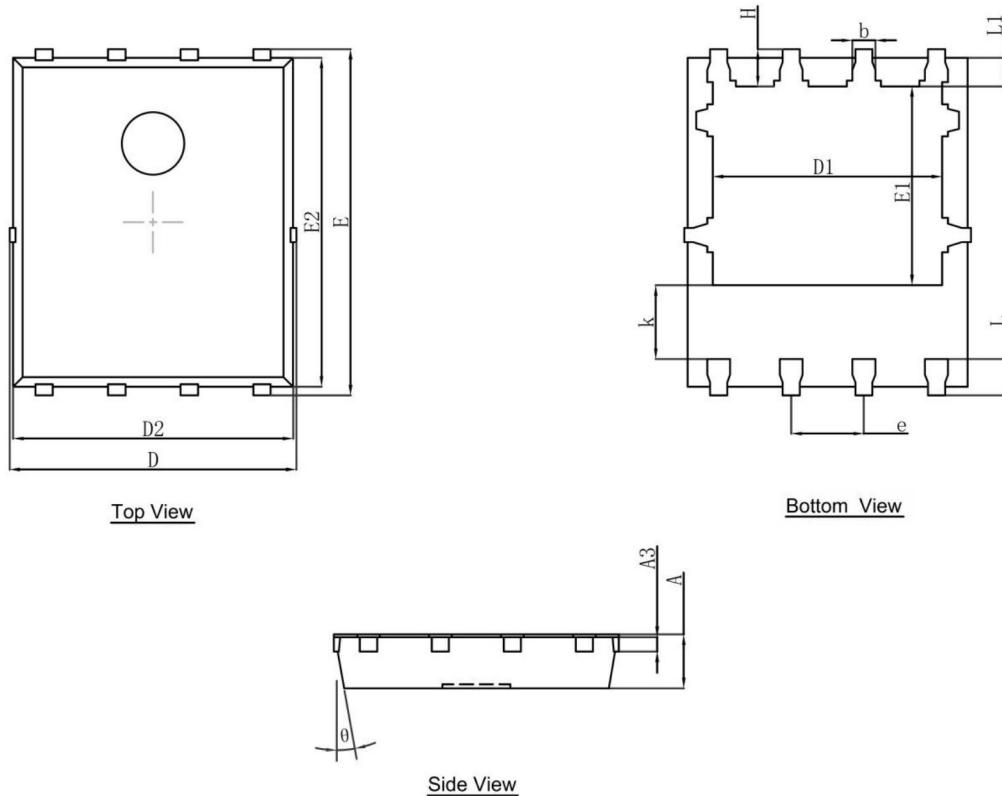


Single Pulse Power Rating, Junction-to-Case



Normalized Maximum Transient Thermal Impedance

DFN5X6-8L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254 REF			0.010 REF
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP			0.050TYP
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	10°			12°